

Low Frequency EMI Reduction

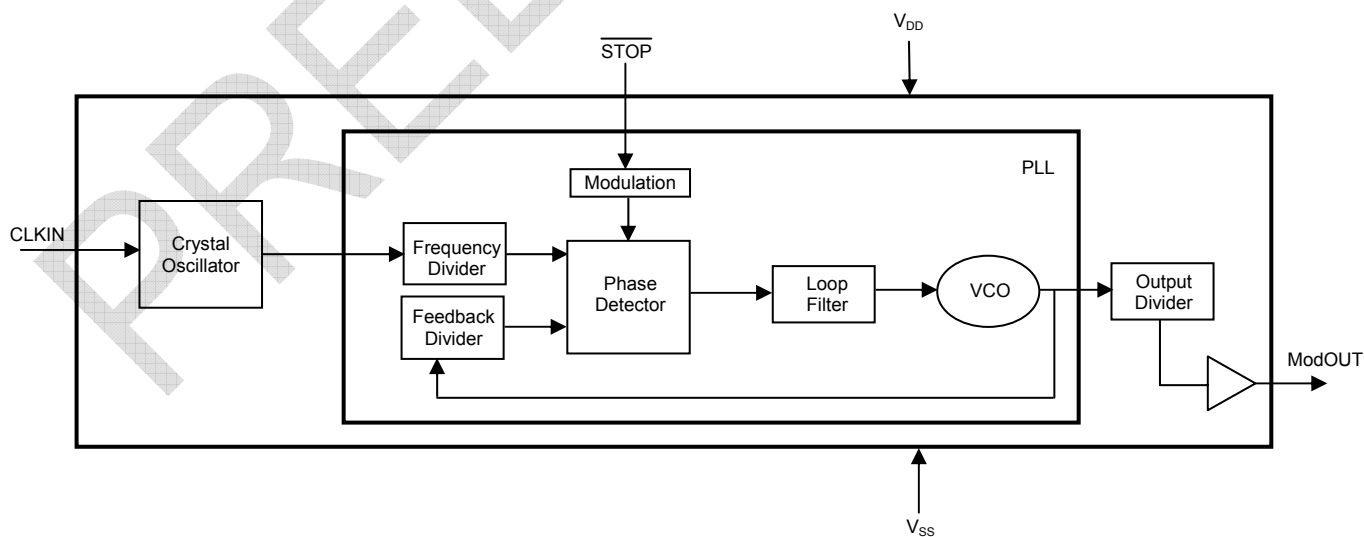
Features

- FCC approved method of EMI attenuation.
- Generates a low EMI spread spectrum of the input clock frequency.
- Optimized for input frequency range between 27MHz – 55MHz.
- Internal loop filter minimizes external components and board space.
- Frequency Deviation: $\pm 1.7\%$.
- Low inherent Cycle-to-cycle jitter.
- 3.3 V \pm 0.3V Operating Voltage.
- Ultra low power CMOS design: 3.0 mA @ 3.3 V.
- Supports notebook VGA and other LCD timing controller applications.
- Available in 8-pin SOIC and TSSOP Packages.

Product Description

The ASM3P2531A is a versatile spread spectrum frequency modulator designed specifically for a wide range of clock frequencies. It reduces electromagnetic interference (EMI) at the clock source allowing system-wide reduction of EMI of downstream clock and data

Block Diagram



dependent signals. It allows significant system cost savings by reducing the number of circuit board layers and shielding traditionally required to pass EMI regulations.

The ASM3P2531A modulates the output of a single PLL in order to spread the bandwidth of a synthesized clock, thereby decreasing the peak amplitudes of its harmonics. This result in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most clock generators. Lowering EMI by increasing a signal's bandwidth is called spread spectrum clock generation.

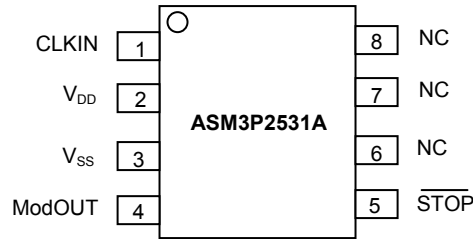
The ASM3P2531A uses the most efficient and optimized modulation profile approved by the FCC and is implemented by using a proprietary all-digital method.

Applications

The ASM3P2531A is targeted toward the notebook VGA chip and other displays using an LVDS interface, PC peripheral devices, and embedded systems.

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Pin Configuration (8-pin SOIC and TSSOP Packages)



Spread Range Selection, V_{DD} = 3.3 V

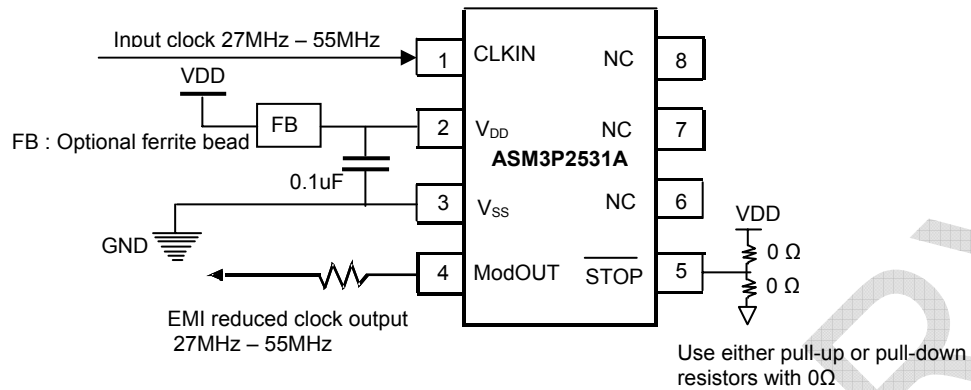
CLKIN frequency	Spreading range	Modulation rate
27MHz – 55MHz	± 1.7%	(CLKIN/1280) KHz

Pin Description

Pin#	Pin Name	Type	Description
1	CLKIN	I	External reference frequency input.
2	V _{DD}	P	Power supply for the entire chip.
3	V _{SS}	P	Ground to entire chip.
4	ModOUT	O	Spread spectrum clock output or reference output.(Refer Standby Mode Selection.)
5	$\overline{\text{STOP}}$	I	Active LOW signal. When HIGH, enables ModOUT and when LOW, ModOUT would be LOW.
6	NC	-	No connect.
7	NC	-	No connect.
8	NC	-	No connect.

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Schematic for a Typical Application



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DD}, V_{IN}	Voltage on any pin with respect to Ground	-0.5 to +4.6	V
T_{STG}	Storage temperature	-65 to +125	°C
T_A	Operating temperature	-40 to +85	°C
T_s	Max. Soldering Temperature (10 sec)	260	°C
T_J	Junction Temperature	150	°C
T_{DV}	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

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DC Electrical Characteristics

Symbol	Parameter		Min	Typ	Max	Unit
V_{IL}	Input low voltage		$V_{SS} - 0.3$		0.8	V
V_{IH}	Input high voltage		2.0		$V_{DD} + 0.3$	V
I_{IL}	Input low current				-35	μA
I_{IH}	Input high current				35	μA
V_{OL}	Output low voltage	$V_{DD} = 3.3\text{V}, I_{OL} = 6\text{ mA}$			0.4	V
V_{OH}	Output high voltage	$V_{DD} = 3.3\text{V}, I_{OH} = 15\text{ mA}$	2.5			V
I_{DD}	Static supply current standby mode			3.0		mA
I_{CC}	Dynamic supply current	3.3V and 15pF loading	10		14	mA
V_{DD}	Operating voltage		3.0	3.3	3.6	V
t_{ON}	Power-up time (first locked cycle after power up)			0.18		mS
Z_{OUT}	Clock output impedance			50		Ω

AC Electrical Characteristics

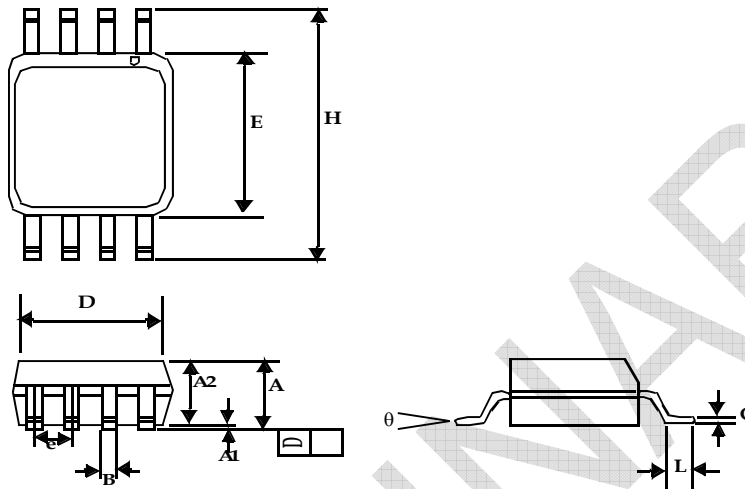
Symbol	Parameter		Min	Typ	Max	Unit
f_{IN}	Input frequency		27		55	MHz
f_{OUT}	Output frequency		27		55	MHz
t_{LH}^1	Output rise time	Measured from 0.8 V to 2.0 V	0.4	0.6	1.2	nS
t_{HL}^1	Output fall time	Measured from 2.0 V to 0.8 V	0.4	0.6	1.2	nS
t_{JC}	Jitter (Cycle to cycle)				360	pS
T_D	Output duty cycle		45	50	55	%

Note 1: t_{LH} and t_{HL} are measured into a capacitive load of 15pF

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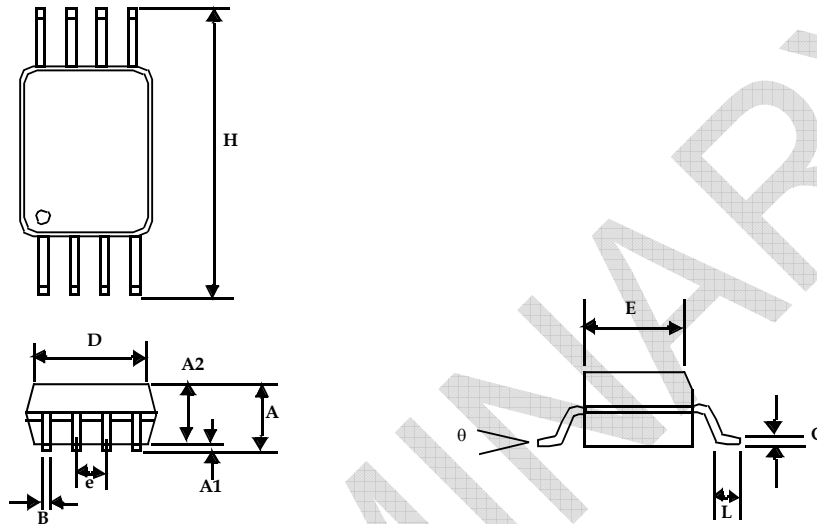
Package Information

8-lead (150-mil) SOIC Package



Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A1	0.004	0.010	0.10	0.25
A	0.053	0.069	1.35	1.75
A2	0.049	0.059	1.25	1.50
B	0.012	0.020	0.31	0.51
C	0.007	0.010	0.18	0.25
D	0.193 BSC		4.90 BSC	
E	0.154 BSC		3.91 BSC	
e	0.050 BSC		1.27 BSC	
H	0.236 BSC		6.00 BSC	
L	0.016	0.050	0.41	1.27
theta	0°	8°	0°	8°

8-lead Thin Shrunk Small Outline Package (4.40-MM Body)



Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A		0.043		1.10
A1	0.002	0.006	0.05	0.15
A2	0.033	0.037	0.85	0.95
B	0.008	0.012	0.19	0.30
c	0.004	0.008	0.09	0.20
D	0.114	0.122	2.90	3.10
E	0.169	0.177	4.30	4.50
e	0.026 BSC		0.65 BSC	
H	0.252 BSC		6.40 BSC	
L	0.020	0.028	0.50	0.70
θ	0°	8°	0°	8°

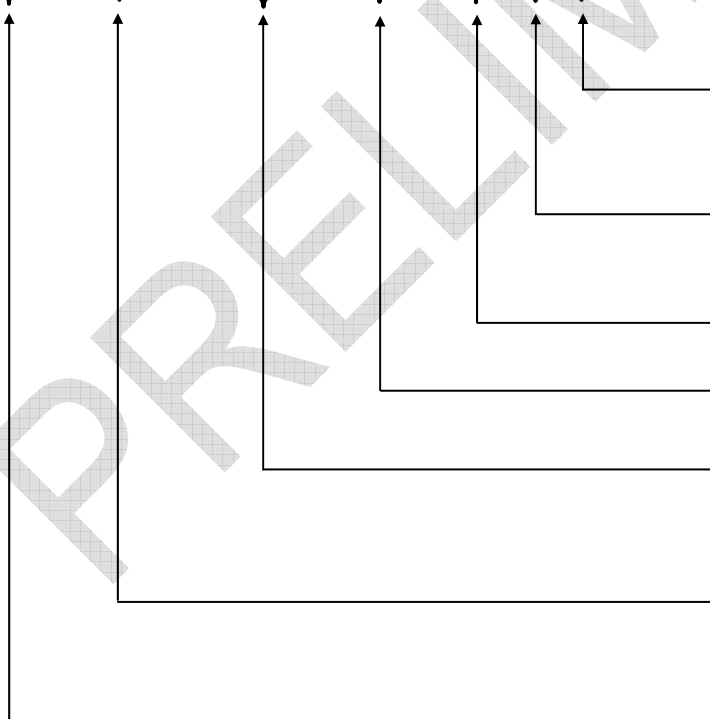
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Ordering Information

Ordering Code	Marking	Package Type	Operating Range
ASM3P2531AF-08ST	3P2531AF	8-pin 150mil SOIC –TUBE, Pb free	Commercial
ASM3P2531AF-08SR	3P2531AF	8-pin 150-mil SOIC -TAPE & REEL, Pb free	Commercial
ASM3I2531AF-08ST	3P2531AF	8-pin 150mil SOIC -TUBE, Pb free	Industrial
ASM3I2531AF-08SR	3P2531AF	8-pin 150-mil SOIC -TAPE & REEL, Pb free	Industrial
ASM3P2531AF-08TT	3P2531AF	8-pin 4.4mm TSSOP -TUBE, Pb free	Commercial
ASM3P2531AF-08TR	3P2531AF	8-pin 4.4mm TSSOP -TAPE & REEL, Pb free	Commercial
ASM3I2531AF-08TT	3P2531AF	8-pin 4.4mm TSSOP -TUBE, Pb free	Industrial
ASM3I2531AF-08TR	3P2531AF	8-pin 4.4mm TSSOP - TAPE & REEL, Pb free	Industrial
ASM3P2531AG-08ST	3P2531AG	8-pin 150mil SOIC –TUBE, Green	Commercial
ASM3P2531AG-08SR	3P2531AG	8-pin 150-mil SOIC -TAPE & REEL, Green	Commercial
ASM3I2531AG-08ST	3P2531AG	8-pin 150mil SOIC -TUBE, Green	Industrial
ASM3I2531AG-08SR	3P2531AG	8-pin 150-mil SOIC -TAPE & REEL, Green	Industrial
ASM3P2531AG-08TT	3P2531AG	8-pin 4.4mm TSSOP -TUBE, Green	Commercial
ASM3P2531AG-08TR	3P2531AG	8-pin 4.4mm TSSOP -TAPE & REEL, Green	Commercial
ASM3I2531AG-08TT	3P2531AG	8-pin 4.4mm TSSOP -TUBE, Green	Industrial
ASM3I2531AG-08TR	3P2531AG	8-pin 4.4mm TSSOP - TAPE & REEL, Green	Industrial

Device Ordering Information

A S M 3 P 2 5 3 1 A F - 0 8 T R



R = Tape & Reel, T = Tube or Tray	
O = SOT S = SOIC T = TSSOP A = SSOP V = TVSOP B = BGA Q = QFN	U = MSOP E = TQFP L = LQFP U = MSOP P = PDIP D = QSOP X = SC-70
DEVICE PIN COUNT	
F = LEAD FREE AND RoHS COMPLIANT PART G = GREEN PACKAGE, LEAD FREE, and RoHS	
DEVICE NUMBER	
X= Automotive (-40C to +125C)	I= Industrial (-40C to +85C)
P or n/c = Commercial (0C to +70C)	
1 = Reserved 2 = Non PLL based 3 = EMI Reduction 4 = DDR support products 5 = STD Zero Delay Buffer	6 = Power Management 7 = Power Management 8 = Power Management 9 = Hi Performance 0 = Reserved
PulseCore Semiconductor Mixed Signal Product	

Licensed under US patent #5,488,627, #6,646,463 and #5,631,920.



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Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to PulseCore Semiconductor, dated 11-11-2003

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